AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (currently amended): A multilayer ceramic substrate with a cavity comprising:

a multilayer composite member including a plurality of ceramic layers disposed one on another;

a cavity formed in the multilayer composite member such that an opening of the cavity is located in at least one principal surface of the multilayer composite member;

a bottom-surface conductive film connected to a ground potential, the bottom-surface conductive film being disposed on a bottom surface of the cavity;

a plurality of conductive films disposed in the multilayer composite member; and

an electronic component electrically connected to the bottom-surface conductive film, the electronic component being disposed in the cavity;

~~a capacitor conductive film disposed in the multilayer composite member such that the capacitor conductive film faces the bottom-surface conductive film via at least one ceramic layer; and~~

~~an electronic circuit disposed in the multilayer composite member;~~ wherein

~~the bottom surface conductive film is connected to a ground potential;~~

~~the bottom-surface conductive film and the capacitor conductive film define a capacitor; and~~

~~a portion of the electronic circuit is connected to the ground potential through the capacitor defined by the bottom-surface conductive film and the capacitor conductive film~~

among the plurality of conductive films, the conductive film which is disposed closest to the bottom-surface conductive film is arranged in the multilayer composite

member so as to define a capacitor conductive film which faces the bottom-surface conductive film via at least one of the plurality of ceramic layers to produce a capacitance, the capacitor conductive film being arranged such that a space between the bottom-surface conductive film and the capacitor conductive film is smaller than a space between all of the other conductive films of the plurality of conductive films and the capacitor conductive film; and

an area of the capacitor conductive film is smaller than an area of the bottom-surface conductive film, and the capacitor conductive film is symmetrically arranged with respect to a center of the electronic component disposed in the cavity, where the center is defined in a bottom surface direction of the cavity.

Claim 2 (canceled).

Claim 3 (original): The multilayer ceramic substrate with a cavity according to claim 1, wherein the electronic component is adhered on the bottom-surface conductive film via a non-conductive adhesive.

Claim 4 (original): The multilayer ceramic substrate with a cavity according to claim 1, wherein the electronic component is electrically connected to the bottom-surface conductive film.

Claim 5 (original): The multilayer ceramic substrate with a cavity according to claim 1, wherein the bottom-surface conductive film is disposed so as to extend into the inside of the multilayer composite member across an edge of the bottom surface of the cavity.

Claim 6 (withdrawn): The multilayer ceramic substrate with a cavity according to claim 1, wherein the bottom-surface conductive film is disposed so as to extend on the bottom surface of the cavity and within the inside of the cavity.

Claim 7 (original): The multilayer ceramic substrate with a cavity according to claim 1, wherein the capacitor conductive film is disposed so as to face the bottom-surface conductive film via a single ceramic layer.

Claim 8 (original): The multilayer ceramic substrate with a cavity according to claim 1, wherein the capacitor conductive film is constructed in the shape of a strip-line such that distributed constant capacitance is defined between the capacitor conductive film and the bottom-surface conductive film.

Claim 9 (original): The multilayer ceramic substrate with a cavity according to claim 1, wherein an external terminal electrode, which is to be electrically connected to a mounting mother board when the multilayer ceramic substrate is mounted on the mounting mother board, is formed on an outer surface of the multilayer composite member, and the bottom-surface conductive film is electrically connected to the external terminal electrode.

Claim 10 (original): The multilayer ceramic substrate with a cavity according to claim 1, wherein when the multilayer ceramic substrate is mounted on a mounting mother board, the principal surface of the multilayer composite member with the cavity comes into contact with the mounting mother board.

Claim 11 (withdrawn): The multilayer ceramic substrate with a cavity according to claim 1, wherein when the multilayer ceramic substrate is mounted on a mounting

mother board, the principal surface of the multilayer composite member opposite the principal surface with the cavity comes into contact with the mounting mother board.

Claim 12 (withdrawn): The multilayer ceramic substrate with a cavity according to claim 1, further comprising a second bottom-surface conductive film disposed on a bottom surface of the cavity.

Claim 13 (withdrawn): The multilayer ceramic substrate with a cavity according to claim 1, further comprising a second capacitor conductive film disposed in the multilayer composite member such that the capacitor conductive film faces the bottom-surface conductive film via at least one ceramic layer.

Claim 14 (withdrawn): The multilayer ceramic substrate with a cavity according to claim 1, further comprising:

a second bottom-surface conductive film disposed on a bottom surface of the cavity; and

a second capacitor conductive film disposed in the multilayer composite member such that the capacitor conductive film faces the bottom-surface conductive film via at least one ceramic layer.

Claim 15 (withdrawn): The multilayer ceramic substrate with a cavity according to claim 13, wherein at least one of the capacitor conductive film and the second capacitor conductive film is strip-line shaped.

Claim 16 (withdrawn): The multilayer ceramic substrate with a cavity according to claim 14, wherein at least one of the capacitor conductive film and the second capacitor conductive film is strip-line shaped.

Claim 17 (withdrawn): The multilayer ceramic substrate with a cavity according to claim 1, wherein the capacitance between the capacitor conductive film and the bottom-surface conductive film is adjusted by removing an area of the bottom-surface conductive film.

Claim 18 (withdrawn): The multilayer ceramic substrate with a cavity according to claim 17, wherein the area of the bottom-surface conductive film is removed by one of trimming and cutting.

Claim 19 (withdrawn): The multilayer ceramic substrate with a cavity according to claim 1, further comprising an inductor conductive film disposed in the multilayer composite member such that the capacitor conductive film faces the capacitor conductive film via at least one ceramic layer.

Claim 20 (withdrawn): The multilayer ceramic substrate with a cavity according to claim 19, wherein the inductor conductive film, the capacitor conductive film, and the bottom-surface conductive film define a series resonant circuit.

Claim 21 (currently amended): A multilayer ceramic substrate comprising:

a multilayer composite member including a plurality of ceramic layers disposed one on another;

a cavity formed in the multilayer composite member such that an opening of the cavity is located in at least one principal surface of the multilayer composite member;

a bottom-surface conductive film connected to a ground potential, the bottom-surface conductive film being disposed on a bottom surface of the cavity;

a plurality of conductive films disposed in the multilayer composite member;

an electronic component electrically connected to the bottom-surface conductive film, the electronic component being disposed in the cavity; and

~~a capacitor conductive film disposed in the multilayer composite member such that the capacitor conductive film faces the bottom-surface conductive film via at least one ceramic layer;~~

an element disposed in the multilayer composite member;~~ and~~

~~an electronic circuit disposed in the multilayer composite member and including the element;~~ wherein

~~the bottom-surface conductive film is connected to a ground potential;~~

among the plurality of conductive films, the conductive film which is disposed closest to the bottom-surface conductive film is arranged in the multilayer composite member so as to define a capacitor conductive film which faces the bottom-surface conductive film via at least one of the plurality of ceramic layers to produce a capacitance, the capacitor conductive film being arranged such that a space between the bottom-surface conductive film and the capacitor conductive film is smaller than a space between all of the other conductive films of the plurality of conductive films and the capacitor conductive film;

an area of the capacitor conductive film is smaller than an area of the bottom-surface conductive film, and the capacitor conductive film is symmetrically arranged with respect to a center of the electronic component disposed in the cavity, where the center is defined in a bottom surface direction of the cavity; and

the element is electrically connected to one of the capacitor conductive film and the bottom-surface conductive film~~; and~~

~~the capacitor conductive film and the bottom-surface conductive film define a capacitor~~.

Claim 22 (previously presented): The multilayer ceramic substrate according to claim 21, wherein the electronic component is adhered on the bottom-surface conductive film via a non-conductive adhesive.

Claim 23 (previously presented): The multilayer ceramic substrate according to claim 21, wherein the electronic component is electrically connected to the bottom-surface conductive film.

Claim 24 (previously presented): The multilayer ceramic substrate according to claim 21, wherein the bottom-surface conductive film is disposed so as to extend into the inside of the multilayer composite member across an edge of the bottom surface of the cavity.

Claim 25 (withdrawn): The multilayer ceramic substrate according to claim 21, wherein the bottom-surface conductive film is disposed so as to extend on the bottom surface of the cavity and within the inside of the cavity.

Claim 26 (previously presented): The multilayer ceramic substrate according to claim 21, wherein the capacitor conductive film is disposed so as to face the bottom-surface conductive film via a single ceramic layer.

Claim 27 (previously presented): The multilayer ceramic substrate according to claim 21, wherein the capacitor conductive film has a strip-line shape such that distributed constant capacitance is defined between the capacitor conductive film and the bottom-surface conductive film.

Claim 28 (previously presented): The multilayer ceramic substrate according to claim 21, wherein an external terminal electrode, which is to be electrically connected to a mounting mother board when the multilayer ceramic substrate is mounted on the mounting mother board, is located on an outer surface of the multilayer composite member, and the bottom-surface conductive film is electrically connected to the external terminal electrode.

Claim 29 (previously presented): The multilayer ceramic substrate according to claim 21, wherein when the multilayer ceramic substrate is mounted on a mounting mother board, the principal surface of the multilayer composite member having the cavity comes into contact with the mounting mother board.

Claim 30 (withdrawn): The multilayer ceramic substrate according to claim 21, wherein when the multilayer ceramic substrate is mounted on a mounting mother board, the principal surface of the multilayer composite member opposite the principal surface with the cavity comes into contact with the mounting mother board.

Claim 31 (withdrawn): The multilayer ceramic substrate according to claim 21, further comprising a second bottom-surface conductive film disposed on a bottom surface of the cavity.

Claim 32 (withdrawn): The multilayer ceramic substrate according to claim 21, further comprising a second capacitor conductive film disposed in the multilayer composite member such that the capacitor conductive film faces the bottom-surface conductive film via at least one ceramic layer.

Claim 33 (withdrawn): The multilayer ceramic substrate according to claim 21, further comprising:

a second bottom-surface conductive film disposed on a bottom surface of the cavity; and

a second capacitor conductive film disposed in the multilayer composite member such that the capacitor conductive film faces the bottom-surface conductive film via at least one ceramic layer.

Claim 34 (withdrawn): The multilayer ceramic substrate according to claim 32, wherein at least one of the capacitor conductive film and the second capacitor conductive film is strip-line shaped.

Claim 35 (withdrawn): The multilayer ceramic substrate according to claim 33, wherein at least one of the capacitor conductive film and the second capacitor conductive film is strip-line shaped.

Claim 36 (withdrawn): The multilayer ceramic substrate according to claim 21, wherein the capacitance between the capacitor conductive film and the bottom-surface conductive film is adjusted by removing an area of the bottom-surface conductive film.

Claim 37 (withdrawn): The multilayer ceramic substrate according to claim 36, wherein the area of the bottom-surface conductive film is removed by one of trimming and cutting.

Claim 38 (withdrawn): The multilayer ceramic substrate according to claim 21, further comprising an inductor conductive film disposed in the multilayer composite member such that the capacitor conductive film faces the capacitor conductive film via at least one ceramic layer.

Claim 39 (withdrawn): The multilayer ceramic substrate according to claim 38, wherein the inductor conductive film, the capacitor conductive film, and the bottom-surface conductive film define a series resonant circuit.